

# Rapixo CXP Pro Octo CXP-12 frame grabber

## Eight-channel CXP-12, performance-built for next-generation data rates and multi-camera systems

The Rapixo CXP Pro Octo CXP-12 pushes CoaXPress frame grabber performance into a new generation. Built to fully leverage the speed and bandwidth increases of the CXP 2.1 standard, it delivers eight CXP-12 connections and massive data throughput for multi-camera, high-resolution, and high-frame-rate applications.

With 16 GB of onboard memory, advanced image-processing hardware, and a PCIe Gen3 x16 interface, the Rapixo CXP Pro Octo CXP-12 keeps pace with today's fastest sensors while maintaining rock-solid reliability. This platform is engineered for demanding machine vision tasks—from inspecting electronics or electric vehicle batteries to laser line extraction and web inspection requiring uncompromising data rates.



### Engineered for the latest CXP 2.1 requirements

This frame grabber is built specifically to exploit the higher speeds and expanded capabilities of CoaXPress 2.1. Whether you're pushing ultra-high data rates, optimizing system latency, or scaling camera counts, the Rapixo CXP Pro Octo CXP-12 provides a future-proof foundation for next-generation machine vision designs.

### Keeps data flowing freely

A full-bandwidth PCIe Gen3 x16 interface ensures that data flows from camera to host without bottlenecks. Even in high-demand applications—large sensors, long bursts, or simultaneous multi-camera capture—the board maintains consistent throughput and deterministic performance.

### Handles high data demands

#### Next-generation throughput for multi-camera systems

With eight independent CXP-12 connections and up to 17 streams, Zebra's Rapixo CXP Pro Octo CXP-12 handles massive aggregate bandwidth with ease. It's ideal for machine vision systems that rely on multiple high-resolution cameras running at high frame rates—delivering the performance needed for complex inspection, 3D imaging, line scan imaging, or synchronized imaging workflows.

**Leverage the speeds and bandwidths available with CXP 2.1, perfect for multi-camera systems**

For more information, please visit [www.zebra.com/rapixo-series](http://www.zebra.com/rapixo-series).

## Onboard processing increases speed

### Built-in image processing to offload the host

Integrated lookup tables (LUTs), Bayer interpolation, and advanced color space conversions let the board handle preprocessing tasks directly. This offloads the CPU/GPU, shortens pipelines, and improves system responsiveness—especially valuable in real-time inspection or when dealing with high-bit-depth and multi-channel imagery.

### Flexible FPGA-based custom processing

Developers can embed their own accelerated processing using the AMD Vivado™ Design Suite and Zebra's FDK. Whether it's handling custom preprocessing or application-specific logic, the Rapixo CXP Pro Octo CXP-12 gives teams a fast, programmable hardware path without the need for external compute modules.

### Stable high-speed capture with deep onboard memory

The 16 GB onboard DDR4 memory provides ample buffering for high-bandwidth bursts, multi-camera concurrency, or hosts under variable loads. This ensures uninterrupted acquisition even in demanding real-time systems.

## Suited to complex and harsh environments

### Easy system integration with robust, high-density I/O

Multiple TTL, LVDS, and opto-isolated I/Os per connector allow precise triggering, strobes, synchronization, and machine-control signaling. With support for inter-board timing and optional HD15 breakout accessories, the board integrates cleanly into complex automation environments.

### PoCXP power delivery simplifies system design

With up to 96 W of combined PoCXP capability, Zebra's Rapixo CXP Pro Octo CXP-12 powers multiple cameras directly, reducing cabling, eliminating external power supplies, and simplifying machine vision buildouts—especially in space-constrained or mobile systems.

### Reliable operation in manufacturing and harsh use cases

Active cooling and wide operating temperatures support deployment in industrial environments. Status LEDs provide quick diagnostics at a glance, helping reduce downtime during integration, maintenance, or troubleshooting.

# Specifications

Physical characteristics	
<b>Dimensions</b>	9.84 inches L x 0.737 inch W x 4.39 inches H 24.99 cm L x 1.871 cm W x 11.15 cm H
<b>Form factor</b>	Full height, 3/4 length PCIe x16
<b>Connectors</b>	High-density BNC
<b>Configuration</b>	Eight (8) connections in
<b>Streams</b>	Up to seventeen (17) total
<b>Status indicators</b>	Connection status LEDs on inputs
<b>Cooling</b>	Active (fan)
Performance characteristics	
<b>Speed</b>	12.5 Gbps (CXP-12)
<b>Acquisition standard</b>	CoaXPress 2.1
<b>GenICam support</b>	GenICam 3.4
<b>PC interconnect</b>	PCIe Gen3 x16
<b>Memory</b>	16 GB DDR4 DRAM
<b>Power output</b>	PoCXP (up to 96 W total)
Image processing	
<b>Onboard lookup tables</b>	8/10/12 bit support
<b>Onboard Bayer interpolation</b>	GB, BG, GR, and RG pattern support
<b>Onboard color space conversion</b>	Input formats: 8/16 bit mono/Bayer, 24/48 bit packed BGR Output formats: 8/16 bit mono, 24/48 bit packed/planar BGR, 16 bit YUV, 16 bit YCbCr, 32 bit BGRA
<b>Custom processing</b>	Zebra or user developed (AMD Vivado Design Suite and Zebra FDK)

I/Os	
<b>Per HD15 connector</b>	Three (3) TTL I/Os
	Two (2) LVDS inputs
	One (1) LVDS output
	Two (2) opto-isolated inputs
<b>External connectors</b>	Four (4) HD15 connectors (via accessory brackets)
<b>Internal connectors</b>	One (1) 9-pin USB header
	One (1) 12-pin connector for synchronization header
User environment	
<b>Operating temperature</b>	32°F to 131°F (0°C to 55°C)
<b>Relative humidity (non-condensing)</b>	Up to 95%
<b>Cooling</b>	Active (fan)
Certifications	
<b>Electromagnetic compatibility</b>	FCC Class A
	CE Class A (EN55032, EN55024)
	ICES-003/NMB-003 Class A
	RCM Class A
Software	
<b>Compatible software</b>	Aurora Imaging Library (Lite) 10.70 with update 157
	Aurora Imaging Library (Lite) 11 with update 9
<b>Operating systems</b>	Windows 11
	Ubuntu 24.04 LTS (64 bits)

## Markets and applications

### General manufacturing

- Multi-camera inspection systems
- High-speed packaging and labeling verification
- Web inspection
- Inline defect detection and dimensional metrology

### Electronics and semiconductors

- High-speed inspection
- PCB and IC inspection
- Wafer and die inspection
- Flat panel display (FPD) inspection
- Laser line extraction

### Automotive and EV

- Weld seam and surface inspection
- Paint and finish defect detection
- EV battery cell/module inspection
- Web inspection
- High-speed component verification
- Multi-view, safety-critical inspection